

Industrial communication networks - Fieldbus
specifications - Part 2: Physical layer specification and
service definition

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

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English Version

Industrial communication networks - Fieldbus specifications -
Part 2: Physical layer specification and service definition
(IEC 61158-2:2023)

Réseaux de communication industriels - Spécifications des
bus de terrain - Partie 2: Spécification et définition des
services de la couche physique
(IEC 61158-2:2023)

Industrielle Kommunikationsnetze - Feldbusse - Teil 2:
Spezifikation und Dienstfestlegungen des Physical Layer
(Bitübertragungsschicht)
(IEC 61158-2:2023)

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European foreword

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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Industrial communication networks – Fieldbus specifications –
Part 2: Physical layer specification and service definition**

**Réseaux de communication industriels – Spécifications des bus de terrain –
Partie 2: Spécification et définition des services de la couche physique**



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Partie 2: Spécification et définition des services de la couche physique**

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CONTENTS

FOREWORD.....	36
0 INTRODUCTION	38
0.1 General.....	38
0.2 Physical layer overview.....	38
0.3 Document overview.....	38
0.4 Major physical layer variations specified in this document.....	39
0.4.1 Type 1 media	39
0.4.1.1 Type 1: Wire media	39
0.4.1.2 Type 1: Optical media	39
0.4.2 Type 2: Coaxial wire and optical media	39
0.4.3 Type 3: Twisted-pair wire and optical media.....	39
0.4.4 Type 4: Wire medium	40
0.4.5 Type 8: Twisted-pair wire and optical media.....	40
0.4.6 Type 12: Wire medium	40
0.4.7 Type 16: optical media.....	40
0.4.8 Type 18: Media	40
0.4.8.1 Type 18: Basic media.....	40
0.4.8.2 Type 18: Powered media	40
0.4.9 Type 20: Media	41
0.4.10 Type 24: Media	41
0.4.10.1 Type 24: Basic media	41
0.4.10.2 Type 24: Powered media	41
0.4.11 Type 28: Media	41
0.5 Patent declaration.....	41
1 Scope.....	43
2 Normative references	43
3 Terms and definitions	46
3.1 Common terms and definitions.....	46
3.2 Type 1: Terms and definitions	50
3.3 Type 2: Terms and definitions	53
3.4 Type 3: Terms and definitions	57
3.5 Type 4: Terms and definitions	60
3.6 Void	61
3.7 Type 8: Terms and definitions	61
3.8 Type 12: Terms and definitions	64
3.9 Type 16: Terms and definitions	64
3.10 Type 18: Terms and definitions	67
3.11 Type 24: Terms and definitions	68
3.12 Type 20: Terms and definitions	70
3.13 Type 28: Terms and definitions	72
4 Symbols and abbreviated terms.....	74
4.1 Symbols.....	74
4.1.1 Type 1: Symbols.....	74
4.1.2 Type 2: Symbols.....	75
4.1.3 Type 3: Symbols.....	76
4.1.4 Type 4: Symbols.....	76
4.1.5 Void.....	76

4.1.6	Type 8: Symbols	76
4.1.7	Type 12: Symbols	77
4.1.8	Type 16: Symbols	77
4.1.9	Type 18: Symbols	77
4.1.10	Type 24: Symbols	78
4.1.11	Type 20: Symbols	78
4.1.12	Type 28: Symbols	78
4.2	Abbreviated terms	79
4.2.1	Type 1: Abbreviations	79
4.2.2	Type 2: Abbreviations	80
4.2.3	Type 3: Abbreviations	80
4.2.4	Type 4: Abbreviations	82
4.2.5	Void	82
4.2.6	Type 8: Abbreviations	82
4.2.7	Type 12: Abbreviations	84
4.2.8	Type 16: Abbreviations	84
4.2.9	Type 18: Abbreviations	84
4.2.10	Type 24: Abbreviations	85
4.2.11	Type 20: Abbreviations	85
4.2.12	Type 28: Abbreviations	85
5	DLL – PhL interface	86
5.1	General	86
5.2	Type 1: Required services	87
5.2.1	Primitives of the PhS	87
5.2.2	Notification of PhS characteristics	88
5.2.3	Transmission of Ph-user-data	89
5.2.4	Reception of Ph-user-data	89
5.3	Type 2: Required services	89
5.3.1	General	89
5.3.2	M_symbols	89
5.3.3	PH-LOCK indication	90
5.3.4	PH-FRAME indication	90
5.3.5	PH-CARRIER indication	90
5.3.6	PH-DATA indication	90
5.3.7	PH-STATUS indication	90
5.3.8	PH-DATA request	91
5.3.9	PH-FRAME request	91
5.3.10	PH-JABBER indication	91
5.3.11	Ph-JABBER-CLEAR request	91
5.3.12	Ph-JABBER-TYPE request	91
5.4	Type 3: Required services	92
5.4.1	Synchronous transmission	92
5.4.2	Asynchronous transmission	92
5.5	Type 4: Required services	93
5.5.1	General	93
5.5.2	Primitives of the PhS	93
5.5.3	Transmission of Ph-user data	94
5.6	Void	94
5.7	Type 8: Required services	95

5.7.1	General	95
5.7.2	Primitives of the PhS	95
5.7.3	Overview of the Interactions	96
5.8	Type 12: Required services.....	102
5.9	Type 16: Required services.....	103
5.9.1	Primitives of the PhS	103
5.9.2	Transmission of Ph-user-data	103
5.9.3	Reception of Ph-user-data	104
5.10	Type 18: Required services.....	104
5.10.1	General	104
5.10.2	Primitives of the PhS	104
5.10.3	Transmission of Ph-user-data	105
5.10.4	Reception of Ph-user-data	105
5.11	Type 24: Required services.....	105
5.11.1	General	105
5.11.2	DL_Symbols	106
5.11.3	PLS_CARRIER indication	106
5.11.4	PLS_SIGNAL indication	106
5.11.5	PLS_DATA_VALID indication.....	106
5.11.6	PLS_DATA indication	106
5.11.7	PLS_DATA request.....	106
5.12	Type 20: Required services.....	106
5.12.1	Facilities of the physical layer services	106
5.12.2	Sequence of primitives	107
5.12.3	PH-START service	107
5.12.4	PH-DATA service	108
5.12.5	PH-END service	108
5.13	Type 28: Required services.....	109
5.13.1	General	109
5.13.2	Ph-Param (para, value).....	109
5.13.3	Ph-Data (length, data, status).....	110
5.13.4	Ph-Clock-Sync (command, data, ofdm timing).....	111
6	Systems management – PhL interface	112
6.1	General.....	112
6.2	Type 1: Systems management – PhL interface.....	112
6.2.1	Required services	112
6.2.2	Service primitive requirements.....	112
6.3	Type 3: Systems management – PhL interface.....	114
6.3.1	Synchronous transmission	114
6.3.2	Asynchronous transmission	114
6.4	Type 4: Systems management – PhL interface.....	119
6.4.1	Required Services	119
6.4.2	Service primitive requirements.....	120
6.5	Void	120
6.6	Type 8: Systems management – PhL interface.....	120
6.6.1	Functionality of the PhL Management	120
6.6.2	PhL-PNM1 Interface	120
6.7	Type 12: Systems management – PhL interface.....	125
6.8	Type 18: Systems management – PhL interface.....	125

6.8.1	General	125
6.8.2	Required services	125
6.8.3	Service primitive requirements	125
6.9	Type 24: Systems management – PhL interface	126
6.10	Type 28: Systems management – PhL interface	126
6.10.1	General	126
6.10.2	PhL related management information table	126
6.10.3	Service primitive	132
7	DCE independent sublayer (DIS)	135
7.1	General	135
7.2	Type 1: DIS	136
7.3	Type 3: DIS	136
7.3.1	Synchronous transmission	136
7.3.2	Asynchronous transmission	136
7.4	Void	136
7.5	Type 8: DIS	136
7.5.1	General	136
7.5.2	Function	136
7.5.3	Serial transmission	136
7.5.4	MDS coupling	137
7.6	Type 12: DIS	138
7.7	Type 28: DIS	138
8	DTE – DCE interface and MIS-specific functions	138
8.1	General	138
8.2	Type 1: DTE – DCE interface	139
8.2.1	Services	139
8.2.2	Signaling interfaces	140
8.3	Type 3: DTE – DCE interface	149
8.3.1	Synchronous transmission	149
8.3.2	Asynchronous transmission	149
8.4	Type 8: MIS – MDS interface	150
8.4.1	General	150
8.4.2	Services	150
8.4.3	Interface signals	151
8.4.4	Converting the services to the interface signals	152
8.5	Type 12: DTE – DCE interface	159
8.6	Type 28: DTE – DCE interface and MIS Specific function	159
8.6.1	General	159
8.6.2	MIS Specific function	159
8.6.3	DTE – DCE interface	166
9	Medium dependent sublayer (MDS)	168
9.1	General	168
9.2	Type 1: MDS: Wire and optical media	168
9.2.1	PhPDU	168
9.2.2	Encoding and decoding	168
9.2.3	Polarity detection	170
9.2.4	Start of frame delimiter	170
9.2.5	End of frame delimiter	170
9.2.6	Preamble	170

9.2.7	Synchronization	171
9.2.8	Post-transmission gap	171
9.2.9	Inter-channel signal skew	171
9.3	Void	171
9.4	Type 2: MDS: Wire and optical media	172
9.4.1	General	172
9.4.2	Clock accuracy	172
9.4.3	Data recovery	172
9.4.4	Data encoding rules	172
9.5	Type 3: MDS: Wire and optical media	173
9.5.1	Synchronous transmission	173
9.5.2	Asynchronous transmission	173
9.6	Type 4: MDS: Wire medium	173
9.6.1	Half-duplex	173
9.6.2	Full-duplex	175
9.6.3	Full-duplex UDP	177
9.7	Void	178
9.8	Type 8: MDS: Wire and optical media	178
9.8.1	Function	178
9.8.2	PhPDU formats	179
9.8.3	Idle states	183
9.8.4	Reset PhPDU	183
9.8.5	MAU coupling	184
9.9	Type 12: MDS: Wire media	185
9.10	Type 16: MDS: Optical media	185
9.10.1	Data encoding rules	185
9.10.2	Telegrams and fill characters	186
9.11	Type 18: MDS: Wire media	186
9.11.1	Overview	186
9.11.2	Transmission	187
9.11.3	Reception	187
9.12	Type 24: MDS: Twisted-pair wire	187
9.12.1	General	187
9.12.2	Clock accuracy	187
9.12.3	Data recovery	188
9.12.4	Data encoding rules	188
9.13	Type 28: MDS: Twisted-pair wire and coaxial media	189
9.13.1	General	189
9.13.2	MDS specification	189
10	MDS – MAU interface	196
10.1	General	196
10.2	Type 1: MDS – MAU interface: Wire and optical media	197
10.2.1	Services	197
10.2.2	Service specifications	197
10.2.3	Signal characteristics	197
10.2.4	Communication mode	198
10.2.5	Timing characteristics	198
10.3	Void	198
10.4	Type 2: MDS – MAU interface: Wire and optical media	198

10.4.1	MDS – MAU interface: general.....	198
10.4.2	MDS – MAU interface: 5 Mbit/s, voltage-mode, coaxial wire.....	199
10.4.3	MDS – MAU interface 5 Mbit/s, optical medium.....	199
10.4.4	MDS – MAU interface Network Access Port (NAP).....	200
10.5	Type 3: MDS – MAU interface: Wire and optical media	200
10.5.1	Synchronous transmission	200
10.5.2	Asynchronous transmission	201
10.6	Type 8: MDS – MAU interface: Wire and optical media	201
10.6.1	Overview of the services.....	201
10.6.2	Description of the services.....	201
10.6.3	Time response.....	202
10.6.4	Transmission mode	202
10.7	Type 18: MDS – MAU interface: Wire media	203
10.7.1	General	203
10.7.2	Services	203
10.7.3	Service specifications	203
10.7.4	Signal characteristics.....	203
10.7.5	Communication mode	204
10.7.6	Timing characteristics	204
10.8	Type 24: MDS – MAU interface: Twisted-pair wire medium	204
10.8.1	Overview of service	204
10.8.2	Description of the services.....	204
10.9	Type 28: MDS – MAU interface: Twisted-pair wire and coaxial media	205
10.9.1	General	205
10.9.2	Services	205
10.9.3	Service process	206
10.9.4	Service specifications	206
10.9.5	Transmit specifications	207
11	Types 1 and 7: Medium attachment unit: voltage mode, linear-bus-topology 150 Ω twisted-pair wire medium	208
11.1	General.....	208
11.2	Bit-rate-dependent quantities	208
11.3	Network specifications	209
11.3.1	Components	209
11.3.2	Topologies.....	209
11.3.3	Network configuration rules	210
11.3.4	Power distribution rules for network configuration	211
11.4	MAU transmit circuit specification	211
11.4.1	Summary	211
11.4.2	MAU test configuration	212
11.4.3	MAU output level requirements	213
11.4.4	MAU output timing requirements	214
11.4.5	Signal polarity.....	215
11.5	MAU receive circuit specification.....	216
11.5.1	Summary	216
11.5.2	Input impedance	216
11.5.3	Receiver sensitivity and noise rejection	217
11.5.4	Received bit cell jitter	217
11.5.5	Interference susceptibility and error rates	217

11.6	Jabber inhibit	218
11.7	Power distribution	218
11.7.1	Overview	218
11.7.2	Supply voltage	219
11.7.3	Powered via signal conductors	219
11.7.4	Powered separately from signal conductors	220
11.7.5	Electrical isolation	220
11.8	Medium specifications	221
11.8.1	Connector	221
11.8.2	Standard test cable	221
11.8.3	Coupler	222
11.8.4	Splices	222
11.8.5	Terminator	222
11.8.6	Shielding rules	222
11.8.7	Grounding (earthing) rules	223
11.8.8	Color coding of cables	223
12	Types 1 and 3: Medium attachment unit: 31,25 kbit/s, voltage-mode with low-power option, bus- and tree-topology, 100 Ω wire medium	223
12.1	General	223
12.2	Transmitted bit rate	224
12.3	Network specifications	224
12.3.1	Components	224
12.3.2	Topologies	224
12.3.3	Network configuration rules	225
12.3.4	Power distribution rules for network configuration	226
12.4	MAU transmit circuit specification	227
12.4.1	Summary	227
12.4.2	MAU test configuration	227
12.4.3	MAU output level requirements	227
12.4.4	Output timing requirements	228
12.4.5	Signal polarity	229
12.4.6	Transition from receive to transmit	229
12.5	MAU receive circuit specification	229
12.5.1	Summary	229
12.5.2	Input impedance	230
12.5.3	Receiver sensitivity and noise rejection	230
12.5.4	Received bit cell jitter	230
12.5.5	Interference susceptibility and error rates	230
12.6	Jabber inhibit	231
12.7	Power distribution	231
12.7.1	General	231
12.7.2	Supply voltage	232
12.7.3	Powered via signal conductors	232
12.7.4	Power supply impedance	234
12.7.5	Powered separately from signal conductors	237
12.7.6	Electrical isolation	237
12.8	Medium specifications	237
12.8.1	Connector	237
12.8.2	Standard test cable	237

12.8.3	Coupler.....	238
12.8.4	Splices	239
12.8.5	Terminator	239
12.8.6	Shielding rules.....	240
12.8.7	Grounding (earthing) rules.....	240
12.8.8	Color coding of cables	240
12.9	Intrinsic safety	241
12.9.1	General	241
12.9.2	Intrinsic safety barrier	241
12.9.3	Barrier and terminator placement.....	241
12.10	Galvanic isolators	241
13	Type 1: Medium attachment unit: current mode, twisted-pair wire medium	241
13.1	General.....	241
13.2	Transmitted bit rate.....	242
13.3	Network specifications	242
13.3.1	Components	242
13.3.2	Topologies.....	242
13.3.3	Network configuration rules	242
13.3.4	Power distribution rules for network configuration	244
13.4	MAU transmit circuit specification	244
13.4.1	General	244
13.4.2	Test configuration.....	245
13.4.3	Output level requirements.....	245
13.4.4	Output timing requirements.....	245
13.5	MAU receive circuit specification.....	246
13.5.1	General	246
13.5.2	Input impedance	247
13.5.3	Receiver sensitivity and noise rejection	247
13.5.4	Received bit cell jitter	247
13.5.5	Interference susceptibility and error rates	247
13.6	Jabber inhibit	248
13.7	Power distribution	248
13.7.1	General	248
13.7.2	Powered via signal conductors	249
13.7.3	Powered separately from signal.....	249
13.7.4	Electrical isolation	249
13.8	Medium specifications.....	250
13.8.1	Connector.....	250
13.8.2	Standard test cable.....	250
13.8.3	Coupler.....	251
13.8.4	Splices	251
13.8.5	Terminator	251
13.8.6	Shielding rules.....	251
13.8.7	Grounding rules	252
13.8.8	Color coding of cables	252
14	Type 1: Medium attachment unit: current mode (1 A), twisted-pair wire medium	252
14.1	General.....	252
14.2	Transmitted bit rate.....	252
14.3	Network specifications	252

14.3.1	Components	252
14.3.2	Topologies	253
14.3.3	Network configuration rules	253
14.3.4	Power distribution rules for network configuration	255
14.4	MAU transmit circuit specification	255
14.4.1	General	255
14.4.2	Configuration	255
14.4.3	Output level requirements	256
14.4.4	Output timing requirements	256
14.5	MAU receive circuit specification	257
14.5.1	General	257
14.5.2	Input impedance	257
14.5.3	Receiver sensitivity and noise rejection	257
14.5.4	Received bit cell jitter	257
14.5.5	Interference susceptibility and error rates	258
14.6	Jabber inhibit	258
14.7	Power distribution	258
14.7.1	General	258
14.7.2	Powered via signal conductors	259
14.7.3	Powered separately from signal	260
14.7.4	Electrical isolation	260
14.8	Medium specifications	260
14.8.1	Connector	260
14.8.2	Standard test cable	260
14.8.3	Coupler	260
14.8.4	Splices	260
14.8.5	Terminator	260
14.8.6	Shielding rules	261
14.8.7	Grounding rules	261
14.8.8	Color coding of cables	261
15	Types 1 and 7: Medium attachment unit: dual-fiber optical media	261
15.1	General	261
15.2	Bit-rate-dependent quantities	261
15.3	Network specifications	262
15.3.1	Components	262
15.3.2	Topologies	262
15.3.3	Network configuration rules	262
15.4	MAU transmit circuit specifications	263
15.4.1	Test configuration	263
15.4.2	Output level specification	263
15.4.3	Output timing specification	263
15.5	MAU receive circuit specifications	264
15.5.1	General	264
15.5.2	Receiver operating range	264
15.5.3	Maximum received bit cell jitter	264
15.5.4	Interference susceptibility and error rates	265
15.6	Jabber inhibit	266
15.7	Medium specifications	266
15.7.1	Connector	266

15.7.2	Standard test fiber	266
15.7.3	Optical passive star	266
15.7.4	Optical active star	266
16	Type 1: Medium attachment unit: 31,25 kbit/s, single-fiber optical medium	268
16.1	General	268
16.2	Transmitted bit rate	268
16.3	Network specifications	268
16.3.1	Components	268
16.3.2	Topologies	268
16.3.3	Network configuration rules	268
16.4	MAU transmit circuit specifications	269
16.4.1	Test configuration	269
16.4.2	Output level specification	269
16.4.3	Output timing specification	269
16.5	MAU receive circuit specifications	269
16.5.1	General	269
16.5.2	Receiver operating range	269
16.5.3	Maximum received bit cell jitter	269
16.5.4	Interference susceptibility and error rates	269
16.6	Jabber inhibit	269
16.7	Medium specifications	270
16.7.1	Connector	270
16.7.2	Standard test fiber	270
16.7.3	Optical passive star	270
16.7.4	Optical active star	270
17	Void	271
18	Type 2: Medium attachment unit: 5 Mbit/s, voltage-mode, coaxial wire medium	271
18.1	General	271
18.2	Transceiver: 5 Mbit/s, voltage-mode, coaxial wire	272
18.3	Transformer 5 Mbit/s, voltage-mode, coaxial wire	277
18.4	Connector 5 Mbit/s, voltage-mode, coaxial wire medium	278
18.5	Topology 5 Mbit/s, voltage-mode, coaxial wire medium	278
18.6	Taps 5 Mbit/s, voltage-mode, coaxial wire medium	280
18.6.1	Description	280
18.6.2	Requirements	280
18.6.3	Spur	282
18.7	Trunk 5 Mbit/s, voltage-mode, coaxial wire medium	282
18.7.1	Trunk Cable	282
18.7.2	Connectors	283
19	Type 2: Medium attachment unit: 5 Mbit/s, optical medium	283
19.1	General	283
19.2	Transceiver 5 Mbit/s, optical medium	283
19.3	Topology 5 Mbit/s, optical medium	284
19.4	Trunk fiber 5 Mbit/s, optical medium	284
19.5	Trunk connectors 5 Mbit/s, optical medium	285
19.6	Fiber specifications 5 Mbit/s, optical medium	285
20	Type 2: Medium attachment unit: network access port (NAP)	288
20.1	General	288

20.2	Signaling.....	289
20.3	Transceiver.....	290
20.4	Connector.....	290
20.5	Cable.....	290
21	Type 3: Medium attachment unit: synchronous transmission, 31,25 kbit/s, voltage mode, wire medium	291
21.1	General.....	291
21.2	Transmitted bit rate.....	292
21.3	Network specifications	292
21.3.1	Components	292
21.3.2	Topologies.....	293
21.3.3	Network configuration rules	293
21.3.4	Power distribution rules for network configuration	295
21.4	Transmit circuit specification for 31,25 kbit/s voltage-mode MAU	295
21.4.1	Summary	295
21.4.2	Test configuration.....	295
21.4.3	Impedance.....	295
21.4.4	Symmetry	296
21.4.5	Output level requirements.....	298
21.4.6	Output timing requirements.....	298
21.4.7	Signal polarity.....	298
21.5	Receive circuit specification for 31,25 kbit/s voltage-mode MAU	298
21.6	Jabber inhibit	298
21.7	Power distribution	298
21.7.1	General	298
21.7.2	Supply voltage.....	299
21.7.3	Powered via signal conductors	299
21.7.4	Electrical isolation	300
21.8	Medium specifications.....	301
21.8.1	Connector.....	301
21.8.2	Standard test cable.....	301
21.8.3	Coupler.....	301
21.8.4	Splices	301
21.8.5	Terminator	301
21.8.6	Shielding rules.....	302
21.8.7	Grounding rules.....	302
21.8.8	Cable colours	302
21.9	Intrinsic safety	302
21.9.1	General	302
21.9.2	Intrinsic safety barrier.....	302
21.9.3	Barrier and terminator placement.....	303
21.10	Galvanic isolators	303
21.11	Coupling elements	303
21.11.1	General	303
21.11.2	MBP-IS repeater.....	303
21.11.3	MBP-IS – RS 485 signal coupler.....	304
21.12	Power supply	305
21.12.1	General	305
21.12.2	Non-intrinsically safe power supply.....	306

21.12.3	Intrinsically safe power supply	306
21.12.4	Power supply of the category "ib"	307
21.12.5	Power supply in category "ia"	308
21.12.6	Reverse powering	309
22	Type 3: Medium attachment unit: asynchronous transmission, wire medium	309
22.1	Medium attachment unit for non intrinsic safety	309
22.1.1	Characteristics	309
22.1.2	Medium specifications	311
22.1.3	Transmission method	314
22.2	Medium attachment unit for intrinsic safety	315
22.2.1	Characteristics	315
22.2.2	Medium specifications	317
22.2.3	Transmission method	319
22.2.4	Intrinsic safety	323
23	Type 3: Medium attachment unit: asynchronous transmission, optical medium	326
23.1	Characteristic features of optical data transmission	326
23.2	Basic characteristics of an optical data transmission medium	327
23.3	Optical network	327
23.4	Standard optical link	328
23.5	Network structures built from a combination of standard optical links	328
23.6	Bit coding	329
23.7	Optical signal level	329
23.7.1	General	329
23.7.2	Characteristics of optical transmitters	329
23.7.3	Characteristics of optical receivers	331
23.8	Temporal signal distortion	332
23.8.1	General	332
23.8.2	Signal shape at the electrical input of the optical transmitter	332
23.8.3	Signal distortion due to the optical transmitter	332
23.8.4	Signal distortion due to the optical receiver	333
23.8.5	Signal influence due to coupling components	334
23.8.6	Chaining standard optical links	334
23.9	Bit error rate	335
23.10	Connectors for fiber optic cable	335
23.11	Redundancy in optical transmission networks	335
24	Type 4: Medium attachment unit: RS-485	335
24.1	General	335
24.2	Overview of the services	335
24.3	Description of the services	336
24.3.1	Transmit signal (TxS)	336
24.3.2	Transmit enable (TxE)	336
24.3.3	Receive signal (RxS)	336
24.4	Network	336
24.4.1	General	336
24.4.2	Topology	336
24.5	Electrical specification	336
24.6	Time response	336
24.7	Interface to the transmission medium	336
24.8	Specification of the transmission medium	337

24.8.1	Cable connectors.....	337
24.8.2	Cable.....	337
25	Void.....	337
26	Void.....	337
27	Type 8: Medium attachment unit: twisted-pair wire medium	337
27.1	MAU signals.....	337
27.2	Transmission bit rate dependent quantities	338
27.3	Network	338
27.3.1	General	338
27.3.2	Topology	339
27.4	Electrical specification	339
27.5	Time response.....	339
27.6	Interface to the transmission medium.....	339
27.6.1	General	339
27.6.2	Incoming interface	339
27.6.3	Outgoing interface	340
27.7	Specification of the transmission medium.....	340
27.7.1	Cable connectors.....	340
27.7.2	Cable.....	340
27.7.3	Terminal resistor.....	342
28	Type 8: Medium attachment unit: optical media	342
28.1	General.....	342
28.2	Transmission bit rate dependent quantities	343
28.3	Network topology	343
28.4	Transmit circuit specifications	344
28.4.1	Data encoding rules.....	344
28.4.2	Test configuration	344
28.4.3	Output level specification.....	344
28.4.4	Output timing specification.....	345
28.5	Receive circuit specifications	345
28.5.1	Decoding rules	345
28.5.2	Fiber optic receiver operating range	345
28.5.3	Maximum received bit cell jitter.....	345
28.6	Specification of the transmission medium.....	346
28.6.1	Connector.....	346
28.6.2	Fiber optic cable specification: polymer optical fiber cable.....	346
28.6.3	Fiber optic cable specification: plastic clad silica fiber cable	348
28.6.4	Standard test fiber	349
29	Type 12: Medium attachment unit: Power combined with Ethernet Physical Layer Device (PHY).....	349
29.1	Electrical characteristics	349
29.1.1	Relationship to the Ethernet architecture	349
29.1.2	General power requirements.....	352
29.1.3	Power sourcing equipment.....	353
29.1.4	Powered device	354
29.1.5	Inrush current and overload protection.....	354
29.1.6	Dynamic change of current	355
29.1.7	Changes related to worst-case droop of transformer	356

29.1.8	Additional electrical specifications	356
29.2	Medium specifications	357
29.2.1	Connector	357
29.2.2	Wire	357
30	Type 16: Medium attachment unit: optical fiber medium at 2 Mbit/s, 4 Mbit/s, 8 Mbit/s and 16 Mbit/s	357
30.1	Structure of the transmission lines	357
30.2	Time performance of bit transmission	358
30.2.1	Introduction	358
30.2.2	Master and slave in test mode	358
30.2.3	Data rate	360
30.2.4	Input-output performance of the slave	361
30.2.5	Idealized waveform	364
30.3	Connection to the optical fiber	364
30.3.1	Introduction	364
30.3.2	Master connection	365
30.3.3	Slave connection	368
30.3.4	Interactions of the connections	369
31	Type 18: Medium attachment unit: basic medium	370
31.1	General	370
31.2	Data signal encoding	371
31.3	Signal loading	371
31.4	Signal conveyance requirements	371
31.5	Media	371
31.5.1	General	371
31.5.2	Topology	371
31.5.3	Signal cable specifications	373
31.5.4	Media termination	373
31.6	Endpoint and branch trunk cable connectors	373
31.7	Recommended type 18-PhL-B MAU circuitry	373
32	Type 18: Medium attachment unit: powered medium	374
32.1	General	374
32.2	Data signal encoding	375
32.3	Signal loading	375
32.4	Signal conveyance requirements	375
32.5	Media	375
32.5.1	General	375
32.5.2	Topology	375
32.5.3	Topology requirements	377
32.5.4	Signal cable specifications	378
32.5.5	Media termination	378
32.6	Endpoint and branch trunk cable connectors	378
32.6.1	Device connector	378
32.6.2	Flat-cable connector	378
32.6.3	Round cable connector	378
32.6.4	Round cable alternate connector	378
32.6.5	T-branch coupler	379
32.7	Embedded power distribution	379
32.7.1	General	379

32.7.2	Power source	379
32.7.3	Power loading.....	380
32.8	Recommended type 18-PhL-P MAU circuitry	381
32.8.1	General	381
32.8.2	Communications element galvanic isolation	381
32.8.3	Power	382
33	Type 24: Medium attachment unit: twisted-pair wire medium	383
33.1	General.....	383
33.2	Network	383
33.2.1	Component.....	383
33.2.2	Topology	383
33.3	Electrical specification	384
33.4	Medium specifications.....	384
33.4.1	Connector.....	384
33.4.2	Cable.....	385
33.4.3	Grounding and shielding rules	386
33.4.4	Bus terminator.....	386
33.4.5	Bit coding	387
33.4.6	Transceiver control	387
33.4.7	Transformer.....	388
33.4.8	Output level requirement	389
33.4.9	Interface to the transmission medium	389
34	Type 20: Medium attachment unit: FSK medium	391
34.1	Overview.....	391
34.2	PhPDU.....	392
34.2.1	PhPDU structure.....	392
34.2.2	PhPDU transmission.....	392
34.2.3	PhPDU reception	393
34.2.4	Preamble length	393
34.3	Device types	393
34.3.1	General	393
34.3.2	Impedance type	393
34.3.3	Connection type.....	394
34.3.4	Device parameters.....	396
34.4	Network configuration rules.....	396
34.5	Digital transmitter specification	397
34.5.1	Test configuration	397
34.5.2	Bit rate and modulation.....	398
34.5.3	Amplitude	398
34.5.4	Timing	400
34.5.5	Digital signal spectrum	401
34.6	Digital receiver specification	401
34.7	Analog signaling	403
34.7.1	Analog signal spectrum	403
34.7.2	Interference to digital signal.....	403
34.8	Device impedance	404
34.8.1	High impedance device.....	404
34.8.2	Low impedance device	404
34.8.3	Secondary device	404

34.9	Interference to analog and digital signals	405
34.9.1	Connection or disconnection of secondary device	405
34.9.2	Cyclic connection.....	405
34.9.3	Output during silence.....	405
34.10	Non-communicating devices	406
34.10.1	Network power supply.....	406
34.10.2	Barrier	407
34.10.3	Miscellaneous hardware	409
35	Type 28: Twisted-pair wire and coaxial media.....	410
35.1	Overview.....	410
35.2	Network Topology	410
35.3	Electrical specifications.....	411
35.4	Transmission Medium Interface	411
35.5	Medium.....	412
35.5.1	Cable.....	412
35.5.2	Connector.....	413
35.5.3	Terminal resistor.....	413
Annex A	(normative) Type 1: Connector specification	414
A.1	Internal connector for wire medium	414
A.2	External connectors for wire medium	415
A.2.1	General	415
A.2.2	External connector for harsh industrial environments	415
A.2.3	External connector for typical industrial environments.....	418
A.3	External connectors for optical medium.....	420
A.3.1	General	420
A.3.2	External connector for typical industrial environments.....	420
Annex B	(informative) Types 1 and 3: Cable specifications and trunk and spur lengths for the 31,25 kbit/s voltage-mode MAU	422
B.1	Cable description and specifications	422
B.2	Typical trunk and spur lengths	422
Annex C	(informative) Types 1 and 7: Optical passive stars	424
C.1	Definition	424
C.2	Example of attenuations.....	424
Annex D	(informative) Types 1 and 7: Star topology.....	425
D.1	Examples of topology.....	425
D.2	Optical power budget.....	426
D.2.1	General	426
D.2.2	Passive star topology (31,25 kbit/s, single fiber mode, optical MAU).....	426
D.2.3	Active star topology (optical MAU)	426
D.3	Mixed with wire media.....	427
Annex E	(informative) Type 1: Alternate fibers	429
E.1	Alternate fibers for dual-fiber mode.....	429
E.2	Alternate fibers for single-fiber mode	429
Annex F	(normative) Type 2: Connector specification	430
F.1	Connector for coaxial wire medium	430
F.2	Connector for optical medium	430
F.2.1	General requirements	430
F.2.2	Connector for short range optical medium.....	430

F.2.3	Connector for medium and long range optical medium.....	431
F.3	Connector for NAP medium.....	431
Annex G (normative)	Type 2: Repeater machine sublayers (RM, RRM) and redundant PhLs.....	433
G.1	General.....	433
G.2	Repeater machine (RM) sublayer.....	433
G.2.1	Requirements	433
G.2.2	RM sublayer state machine (informative)	434
G.3	Redundant PhL	435
G.4	Ring repeater machine (RRM) sublayer.....	437
G.4.1	Requirements	437
G.4.2	RRM sublayer operation	438
Annex H (informative)	Type 2: Reference design examples.....	444
H.1	MAU: 5 Mbit/s, voltage mode, coaxial wire	444
H.1.1	Transceiver reference design example.....	444
H.1.2	Transformer reference design example.....	447
H.1.3	Tap reference design example.....	447
H.2	Network access port (NAP)	448
Annex I (normative)	Type 3: Connector specification.....	450
I.1	Connector for synchronous transmission.....	450
I.1.1	General	450
I.1.2	Pin assignment of M12 circular connector.....	450
I.1.3	Connection between a tee and a station	451
I.2	Connector for asynchronous transmission.....	451
I.2.1	Connector for non-intrinsic safe asynchronous transmission	451
I.2.2	Connector for intrinsic safe asynchronous transmission.....	452
I.3	Connectors for fiber optic cable	456
I.3.1	Connectors for glass fiber optic cable (850 nm and 1 300 nm wavelength).....	456
I.3.2	Connectors for plastic and glass fiber optic cable (660 nm wavelength).....	456
Annex J (normative)	Type 3: Redundancy of PhL and medium.....	457
Annex K (normative)	Type 3: Optical network topology	458
K.1	Signal flow in an optical network	458
K.2	Connection to a network with echo.....	458
K.3	Connection to a network without echo.....	458
K.4	Optical MAU with echo function.....	459
K.5	Optical MAU without echo function.....	459
K.6	Examples of topology.....	460
K.6.1	General	460
K.6.2	Star topology	460
K.6.3	Ring topology	461
K.6.4	Bus topology.....	461
K.6.5	Tree topology	461
K.6.6	TIA-485-A/ fibre optic converter	462
K.7	Optical power budget.....	463
K.7.1	General	463
K.7.2	Limiting conditions	463
K.7.3	62,5/125 µm multi-mode glass fiber	464
K.7.4	9/125 µm single mode glass fiber	464

K.7.5	980/1 000 µm multi-mode plastic fiber	465
K.7.6	Multi-mode glass fiber 200/230 µm fiber	466
Annex L (informative)	Type 3: Reference design examples for asynchronous transmission, wire medium, intrinsically safe	467
L.1	Bus termination in the communication device	467
L.2	Bus termination in the connector	467
L.3	External bus termination	468
Annex M (normative)	Type 8: Connector specification	469
M.1	External connectors for wire medium	469
M.1.1	Subminiature D connector pin assignment	469
M.1.2	Terminal connector pin assignment	469
M.2	External connectors for fiber optic medium	470
M.3	External connectors for hybrid connectors for IP65 applications	470
Annex N (normative)	Type 16: Connector specification	474
Annex O (normative)	Type 16: Optical network topology	475
O.1	Topology	475
O.2	Optical power budget	476
O.2.1	Optical signals on the transmission line	476
O.2.2	Transmitter specifications	476
O.2.3	Receiver specifications	477
O.2.4	Fiber optic cable	478
O.2.5	System data of the optical transmission path	478
Annex P (informative)	Type 16: Reference design example	480
P.1	Functional principles of the repeater circuit	480
P.2	Attenuation on the transmission line	483
Annex Q (normative)	Type 18: Connector specification	484
Q.1	Overview	484
Q.2	Device connector	484
Q.3	Flat-cable connector	485
Q.4	Round cable connector	486
Q.5	Round cable alternate connector	487
Annex R (normative)	Type 18: Media cable specifications	489
R.1	Type 18-PhL-B cable	489
R.2	Type 18-PhL-P cable	490
R.2.1	Flat cable	490
R.2.2	Round cable – preferred	491
R.2.3	Round cable – alternate	492
Annex S (normative)	Type 24: Connector specification	493
S.1	Overview	493
S.2	Type 24-1 connector	493
S.2.1	Type 24-1 device connector	493
S.2.2	Type 24-1 cable connector	494
S.3	Type 24-2 connector	495
S.3.1	Type 24-2 device connector	495
S.3.2	Type 24-2 cable connector	495
S.4	Type 24-3 connector	495
S.4.1	Type 24-3 device connector	495
S.4.2	Type 24-3 cable connector	497

Annex T (informative) Type 20: Network topology, cable characteristics and lengths, power distribution through barriers, and shielding and grounding.....	499
T.1 Topology examples	499
T.1.1 General	499
T.1.2 Point-to-point current input network	499
T.1.3 Point-to-point current output network	500
T.1.4 Multi-drop network	501
T.1.5 Multi-drop network with analog signaling	502
T.1.6 Series connected network.....	503
T.2 Cable description and specifications	504
T.2.1 General	504
T.2.2 Single pair cable length	505
T.2.3 Multi-pair cable length	518
T.3 Power distribution through barriers	518
T.4 Shielding and grounding	519
Annex U (informative) Type 24: Media cable specifications and Network topologies twisted-pair wire medium	521
U.1 Network	521
U.1.1 Component.....	521
U.1.2 Topology	521
U.2 Medium specifications.....	522
U.2.1 Cable.....	522
U.2.2 Tap.....	525
U.3 Power source wiring.....	525
U.3.1 Overview	525
U.3.2 Power adaptor	526
U.3.3 Power supply.....	527
U.3.4 Power load	527
U.3.5 MAU circuit supporting the Type 24-3 power supply.....	528
U.3.6 Power voltage drop.....	530
Annex V (informative) Type 28: Example of data subframe allocation	533
V.1 Example A	533
V.2 Example B	534
V.3 Example C	535
Annex W (normative) Type 28: RS code generating polynomial	536
Bibliography.....	538
Figure 1 – General model of physical layer	38
Figure 2 – Mapping between data units across the DLL-PhL interface.....	87
Figure 3 – Data service for asynchronous transmission.....	92
Figure 4 – Interactions for a data sequence of a master: identification cycle	97
Figure 5 – Interactions for a data sequence of a master: data cycle	98
Figure 6 – Interactions for a data sequence of a slave: identification cycle.....	99
Figure 7 – Interactions for a data sequence of a slave: data cycle	100
Figure 8 – Interactions for a check sequence of a master	101
Figure 9 – Interactions for a check sequence of a slave	102
Figure 10 – Physical layer data service sequences	107

Figure 11 – Ph-Param service primitive process	109
Figure 12 – Ph-Data service primitive process	111
Figure 13 – Ph-Clock-Sync service primitive process	112
Figure 14 – Reset, Set-value, Get-value	115
Figure 15 – Event service	115
Figure 16 – Interface between PhL and PNM1 in the layer model	120
Figure 17 – Reset, Set-value, Get-value PhL services	121
Figure 18 – Event PhL service	122
Figure 19 – Allocation of the interface number	123
Figure 20 – Resource block information structure	132
Figure 21 – Ph-RESET service primitive process	133
Figure 22 – Ph-SET-VALUE service primitive process	133
Figure 23 – Ph-GET-VALUE service primitive process	134
Figure 24 – Ph-EVENT service primitive process	134
Figure 25 – Ph-SYNC service primitive process	135
Figure 26 – Configuration of a master	137
Figure 27 – Configuration of a slave with an alternative type of transmission	137
Figure 28 – Configuration of a bus coupler with an alternative type of transmission	138
Figure 29 – DTE/DCE sequencing machines	143
Figure 30 – State transitions with the ID cycle request service	152
Figure 31 – MIS-MDS interface: identification cycle request service	153
Figure 32 – MIS-MDS interface: identification cycle request service	154
Figure 33 – State transitions with the data cycle request service	154
Figure 34 – MIS-MDS interface: data cycle request service	155
Figure 35 – State transitions with the data sequence classification service	155
Figure 36 – Protocol machine for the message transmission service	156
Figure 37 – Protocol machine for the data sequence identification service	157
Figure 38 – Protocol machine for the message receipt service	158
Figure 39 – SF and OFDM symbol	160
Figure 40 – SF structure	161
Figure 41 – carrier mode A and carrier mode B of data subframe	162
Figure 42 – OFDM symbol structure of PhL	163
Figure 43 – OFDM timing structure	163
Figure 44 – DLPDU and CB	164
Figure 45 – Resource element schematic diagram	164
Figure 46 – DTE-DCE interface signal process	168
Figure 47 – Protocol data unit (PhPDU)	168
Figure 48 – PhSDU encoding and decoding	169
Figure 49 – Manchester encoding rules	169
Figure 50 – Preamble and delimiters	171
Figure 51 – Manchester coded symbols	173
Figure 52 – PhPDU format, half duplex	173
Figure 53 – PhPDU format, full duplex	176

Figure 54 – Data sequence PhPDU.....	179
Figure 55 – Structure of the header in a data sequence PhPDU.....	179
Figure 56 – Check sequence PhPDU	180
Figure 57 – Structure of a header in a check sequence PhPDU	180
Figure 58 – Structure of the status PhPDU.....	181
Figure 59 – Structure of the header in a status PhPDU	181
Figure 60 – Structure of the medium activity status PhPDU.....	182
Figure 61 – Structure of the header in a medium activity status PhPDU	182
Figure 62 – Reset PhPDU	183
Figure 63 – Configuration of a master	184
Figure 64 – Configuration of a slave	185
Figure 65 – Configuration of a bus coupler.....	185
Figure 66 – Example of an NRZI-coded signal	186
Figure 67 – Fill signal	186
Figure 68 – Manchester coded symbols	188
Figure 69 – NRZI coded symbols	189
Figure 70 – PhL channel process	190
Figure 71 – Scrambling sequence generation	190
Figure 72 – Convolutional encoder with a code rate of 1/2	192
Figure 73 – Bit deletion process with code rates 2/3 and 3/4.....	193
Figure 74 – Generation of m sequence	194
Figure 75 – OFDM symbol structure diagram	195
Figure 76 – Jitter tolerance	202
Figure 77 – MDS-MAU interface service process diagram.....	206
Figure 78 – Signal spectrum template	207
Figure 79 – Transmit circuit test configuration.....	213
Figure 80 – Output waveform.....	213
Figure 81 – Transmitted and received bit cell jitter (zero crossing point deviation)	214
Figure 82 – Signal polarity	216
Figure 83 – Receiver sensitivity and noise rejection.....	217
Figure 84 – Power supply ripple and noise.....	220
Figure 85 – Fieldbus coupler.....	222
Figure 86 – Transition from receiving to transmitting.....	229
Figure 87 – Power supply ripple and noise.....	233
Figure 88 – Test circuit for single-output power supplies.....	234
Figure 89 – Test circuit for power distribution through an IS barrier	235
Figure 90 – Test circuit for multiple output supplies with signal coupling	236
Figure 91 – Fieldbus coupler.....	238
Figure 92 – Protection resistors	239
Figure 93 – Test configuration for current-mode MAU	245
Figure 94 – Transmitted and received bit cell jitter (zero crossing point deviation)	246
Figure 95 – Noise test circuit for current-mode MAU	248
Figure 96 – Transmitted and received bit cell jitter (zero crossing point deviation)	256

Figure 97 – Power supply harmonic distortion and noise	259
Figure 98 – Optical wave shape template	264
Figure 99 – Components of 5 Mbit/s, voltage-mode, coaxial wire PhL variant	272
Figure 100 – Coaxial wire MAU block diagram	272
Figure 101 – Coaxial wire MAU transmitter	273
Figure 102 – Coaxial wire MAU receiver operation	274
Figure 103 – Coaxial wire MAU transmit mask	275
Figure 104 – Coaxial wire MAU receive mask	276
Figure 105 – Transformer symbol	277
Figure 106 – 5 Mbit/s, voltage-mode, coaxial wire topology example	279
Figure 107 – Coaxial wire medium topology limits	279
Figure 108 – Coaxial wire medium tap electrical characteristics	281
Figure 109 – MAU block diagram 5 Mbit/s, optical fiber medium	284
Figure 110 – NAP reference model	288
Figure 111 – Example of transient and permanent nodes	289
Figure 112 – NAP transceiver	290
Figure 113 – NAP cable	291
Figure 114 – Circuit diagram of the principle of measuring impedance	296
Figure 115 – Definition of CMRR	297
Figure 116 – Block circuit diagram of the principle of measuring CMRR	297
Figure 117 – Power supply ripple and noise	300
Figure 118 – Output characteristic curve of a power supply of the category EEx ib	308
Figure 119 – Output characteristic curve of a power supply of the category EEx ia	308
Figure 120 – Repeater in linear bus topology	311
Figure 121 – Repeater in tree topology	311
Figure 122 – Example for a connector with integrated inductance	313
Figure 123 – Interconnecting wiring	313
Figure 124 – Bus terminator	314
Figure 125 – Linear structure of an intrinsically safe segment	316
Figure 126 – Topology example extended by repeaters	317
Figure 127 – Bus terminator	319
Figure 128 – Waveform of the differential voltage	320
Figure 129 – Test set-up for the measurement of the idle level for devices with an integrated termination resistor	322
Figure 130 – Test set-up for the measurement of the idle level for devices with a connectable termination resistor	322
Figure 131 – Test set-up for measurement of the transmission levels	323
Figure 132 – Test set-up for the measurement of the receiving levels	323
Figure 133 – Fieldbus model for intrinsic safety	324
Figure 134 – Communication device model for intrinsic safety	324
Figure 135 – Connection to the optical network	327
Figure 136 – Principle structure of optical networking	328
Figure 137 – Definition of the standard optical link	328
Figure 138 – Signal template for the optical transmitter	333

Figure 139 – Recommended interface circuit	337
Figure 140 – MAU of an outgoing interface	338
Figure 141 – MAU of an incoming interface.....	338
Figure 142 – Remote bus link	339
Figure 143 – Interface to the transmission medium	339
Figure 144 – Wiring	342
Figure 145 – Terminal resistor network	342
Figure 146 – Fiber optic remote bus cable	343
Figure 147 – Optical fiber remote bus link.....	343
Figure 148 – Optical wave shape template optical MAU	345
Figure 149 – Combining Ethernet and Power	350
Figure 150 – Interaction between PSE and multiple PD	351
Figure 151 – 2PP power sourcing equipment (PSE) relationship to the physical interface circuitry and the ISO/IEC/IEEE 8802-3 model	351
Figure 152 – 2PP powered device (PD) relationship to the physical interface circuitry and the ISO/IEC/IEEE 8802-3 model.....	352
Figure 153 – Interaction between Port, MDI and PI	352
Figure 154 – Inrush current limits above nominal current	355
Figure 155 – Optical transmission line	357
Figure 156 – Optical signal envelope	360
Figure 157 – Display of jitter (J_{noise}).....	360
Figure 158 – Input-output performance of a slave	362
Figure 159 – Functions of a master connection	365
Figure 160 – Valid transmitting signals during the transition from fill signal to telegram delimiters	367
Figure 161 – Valid transmitting signals during the transition from telegram delimiter to fill signal	368
Figure 162 – Functions of a slave connection	369
Figure 163 – Network with two slaves	370
Figure 164 – Minimum interconnecting wiring.....	371
Figure 165 – Dedicated cable topology	372
Figure 166 – T-branch topology	372
Figure 167 – Communication element isolation	374
Figure 168 – Communication element and I/O isolation.....	374
Figure 169 – Minimum interconnecting wiring.....	375
Figure 170 – Flat cable topology	376
Figure 171 – Dedicated cable topology	376
Figure 172 – T-branch topology	377
Figure 173 – Type 18-PhL-P power distribution.....	379
Figure 174 – Type 18-PhL-P power distribution.....	379
Figure 175 – Type 18-PhL-P power supply filtering and protection	381
Figure 176 – Communication element isolation	382
Figure 177 – Communication element and i/o isolation.....	382
Figure 178 – PhL-P power supply circuit	382

Figure 179 – Expanded Type 24-1 network using repeater.....	384
Figure 180 – Connector with inductor.....	385
Figure 181 – Type 24-1 Cable structure.....	385
Figure 182 – Type 24-1 Interconnecting wiring.....	386
Figure 183 – Type 24-1 Bus terminator.....	387
Figure 184 – Eye pattern for Type 24-1.....	388
Figure 185 – Eye pattern for Type 24-3.....	388
Figure 186 – Type 24-1 Transformer symbol.....	389
Figure 187 – Type 24-1 Recommended MAU circuit.....	390
Figure 188 – Type 24-3 Recommended MAU circuit for upstream port.....	390
Figure 189 – Type 24-3 Recommended MAU circuit for downstream port.....	391
Figure 190 – Phase-continuous Frequency-Shift-Keying.....	391
Figure 191 – PhPDU Structure.....	392
Figure 192 – Character format.....	393
Figure 193 – Transmit test configuration.....	397
Figure 194 – Transmit waveform.....	399
Figure 195 – Carrier start time.....	400
Figure 196 – Carrier stop time.....	401
Figure 197 – Carrier decay time.....	401
Figure 198 – Digital signal spectrum.....	401
Figure 199 – Digital receiver interference.....	402
Figure 200 – Analog signal spectrum.....	403
Figure 201 – Output during silence.....	406
Figure 202 – Network power supply ripple.....	406
Figure 203 – Barrier test circuit A.....	408
Figure 204 – Barrier test circuit B.....	408
Figure 205 – Barrier test circuit C.....	409
Figure 206 – Network topology of Type 28.....	411
Figure 207 – Connector of the shielded twisted pair.....	413
Figure 208 – Terminal resistor.....	413
Figure A.1 – Internal fieldbus connector.....	414
Figure A.2 – Contact designations for the external connector for harsh industrial environments.....	416
Figure A.3 – External fieldbus connector keyways, keys, and bayonet pins and grooves.....	416
Figure A.4 – External fieldbus connector intermateability dimensions.....	417
Figure A.5 – External fieldbus connector contact arrangement.....	418
Figure A.6 – Contact designations for the external connector for typical industrial environments.....	419
Figure A.7 – External fixed (device) side connector for typical industrial environments: dimensions.....	419
Figure A.8 – External free (cable) side connector for typical industrial environments: dimensions.....	420
Figure A.9 – Optical connector for typical industrial environments (FC connector).....	421
Figure A.10 – Optical connector for typical industrial environments (ST connector).....	421

Figure C.1 – Example of an optical passive reflective star.....	424
Figure C.2 – Example of an optical passive transmissive star.....	424
Figure D.1 – Example of star topology with 31,25 kbit/s, single fiber mode, optical MAU.....	425
Figure D.2 – Multi-star topology with an optical MAU	425
Figure D.3 – Example of mixture between wire and optical media for 31,25 kbit/s	427
Figure D.4 – Example of mixture between wire and optical media	428
Figure F.1 – Pin connector for short range optical medium.....	431
Figure F.2 – Crimp ring for short range optical medium.....	431
Figure G.1 – PhL repeater device reference model	433
Figure G.2 – Reference model for redundancy	436
Figure G.3 – Block diagram showing redundant coaxial medium and NAP	437
Figure G.4 – Block diagram showing ring repeaters	437
Figure G.5 – Segmentation query	439
Figure G.6 – Segmentation response	439
Figure G.7 – Main switch state machine.....	441
Figure G.8 – Port 1 sees network activity first.....	442
Figure G.9 – Port 2 sees network activity first.....	443
Figure H.1 – Coaxial wire MAU RXDATA detector	445
Figure H.2 – Coaxial wire MAU RXCARRIER detection.....	446
Figure H.3 – Redundant coaxial wire MAU transceiver.....	446
Figure H.4 – Single channel coaxial wire MAU transceiver.....	447
Figure H.5 – Coaxial wire medium tap.....	448
Figure H.6 – Non-isolated NAP transceiver	449
Figure H.7 – Isolated NAP transceiver	449
Figure I.1 – Schematic of the station coupler	450
Figure I.2 – Pin assignment of the male and female connectors IEC 60947-5-2 (A coding)	451
Figure I.3 – Connector pinout, front view of male and back view of female respectively	452
Figure I.4 – Connector pinout, front view of female M12 connector	454
Figure I.5 – Connector pinout, front view of male M12 connector	454
Figure I.6 – M12 Tee.....	455
Figure I.7 – M12 Bus termination	456
Figure J.1 – Redundancy of PhL MAU and Medium.....	457
Figure K.1 – Optical MAU in a network with echo	458
Figure K.2 – Optical MAU in a network without echo	459
Figure K.3 – Optical MAU with echo via internal electrical feedback of the receive signal.....	459
Figure K.4 – Optical MAU without echo function.....	460
Figure K.5 – Optical network with star topology.....	460
Figure K.6 – Optical network with ring topology.....	461
Figure K.7 – Optical network with bus topology.....	461
Figure K.8 – Tree structure built from a combination of star structures.....	462
Figure K.9 – Application example for a TIA-485-A / fiber optic converter	462
Figure L.1 – Bus termination integrated in the communication device	467

Figure L.2 – Bus termination in the connector	468
Figure L.3 – External bus termination.....	468
Figure M.1 – Outgoing interface 9-position female subminiature D connector at the device	469
Figure M.2 – Incoming interface 9-position male subminiature D connector at the device.....	469
Figure M.3 – Terminal connector at the device.....	469
Figure M.4 – Ferrule of an optical F-SMA connector for polymer optical fiber (980/1 000 µm)	470
Figure M.5 – Type 8 fiber optic hybrid connector housing	471
Figure M.6 – Type 8 fiber optic hybrid connector assignment	472
Figure O.1 – Topology	475
Figure O.2 – Structure of a single-core cable (example).....	478
Figure O.3 – Optical power levels	479
Figure P.1 – Example of an implemented DPLL	481
Figure P.2 – DPLL status diagram	482
Figure P.3 – DPLL timing	482
Figure Q.1 – PhL-P device connector r-a	484
Figure Q.2 – PhL-P device connector straight.....	485
Figure Q.3 – PhL-P flat cable connector and terminal cover - body and connector	485
Figure Q.4 – PhL-P flat cable connector and terminal cover - terminal cover.....	486
Figure Q.5 – Type 18-PhL-P round cable connector body	486
Figure Q.6 – Type 18-PhL-P round cable connector terminal cover.....	487
Figure Q.7 – Type 18-PhL-P round cable alternate connector and body	487
Figure Q.8 – Type 18-PhL-P round cable alternate connector terminal cover	488
Figure R.1 – PhL-B cable cross-section twisted drain.....	489
Figure R.2 – PhL-B cable cross-section non-twisted drain.....	490
Figure R.3 – PhL-P flat cable cross section – with key	491
Figure R.4 – PhL-P flat cable cross section – without key	491
Figure R.5 – PhL-P flat cable polarity marking	491
Figure R.6 – Round cable – preferred; cross section.....	492
Figure R.7 – Round cable – alternate; cross-section	492
Figure S.1 – Type 24-1 device connector dimensions (1 row).....	493
Figure S.2 – Type 24-1 device connector dimensions (2 rows).....	494
Figure S.3 – Type 24-1 cable connector dimensions	494
Figure S.4 – Type 24-3 device 6 pin connector (surface mount type) dimensions.....	495
Figure S.5 – Type 24-3 device 6 pin connector (through-hole mount type) dimensions.....	495
Figure S.6 – Type 24-3 device 6 pin connector (upright through-hole mount type) dimensions	496
Figure S.7 – Type 24-3 device 8 pin male connector dimensions	496
Figure S.8 – Type 24-3 ejector dimensions for device 8 pin male connector.....	497
Figure S.9 – Type 24-3 device 8 pin female connector dimensions	497
Figure S.10 – Type 24-3 cable 6 pin male connector dimensions	498
Figure S.11 – Type 24-3 cable 6 pin female connector dimensions	498

Figure S.12 – Type 24-3 cable 8 pin male connector dimensions	498
Figure S.13 – Type 24-3 cable 8 pin female connector dimensions	498
Figure T.1 – Point-to-point current input network	499
Figure T.2 – Point-to-point current output network	500
Figure T.3 – Multi-drop network	501
Figure T.4 – Multi-drop network with analog signaling	502
Figure T.5 – Series connected network 1	503
Figure T.6 – Series connected network 2	504
Figure T.7 – Cable length for single slave device network	506
Figure T.8 – Cable capacitance for $C_{cbl}/R_{cbl}=1\ 000$	507
Figure T.9 – Cable capacitance for $C_{cbl}/R_{cbl}=2\ 000$	507
Figure T.10 – Cable capacitance for $C_{cbl}/R_{cbl}=5\ 000$	508
Figure T.11 – Cable capacitance for $C_{cbl}/R_{cbl}=10\ 000$	508
Figure T.12 – Cable capacitance for $C_{cbl}/R_{cbl}=1\ 000$, 100 Ω series resistance	509
Figure T.13 – Cable capacitance for $C_{cbl}/R_{cbl}=1\ 000$, 200 Ω series resistance	509
Figure T.14 – Cable capacitance for $C_{cbl}/R_{cbl}=1\ 000$, 300 Ω series resistance	510
Figure T.15 – Cable capacitance for $C_{cbl}/R_{cbl}=1\ 000$, 400 Ω series resistance	510
Figure T.16 – Cable capacitance for $C_{cbl}/R_{cbl}=2\ 000$, 100 Ω series resistance	511
Figure T.17 – Cable capacitance for $C_{cbl}/R_{cbl}=2\ 000$, 200 Ω series resistance	511
Figure T.18 – Cable capacitance for $C_{cbl}/R_{cbl}=2\ 000$, 300 Ω series resistance	512
Figure T.19 – Cable capacitance for $C_{cbl}/R_{cbl}=2\ 000$, 400 Ω series resistance	512
Figure T.20 – Cable capacitance for $C_{cbl}/R_{cbl}=5\ 000$, 100 Ω series resistance	513
Figure T.21 – Cable capacitance for $C_{cbl}/R_{cbl}=5\ 000$, 200 Ω series resistance	513
Figure T.22 – Cable capacitance for $C_{cbl}/R_{cbl}=5\ 000$, 300 Ω series resistance	514
Figure T.23 – Cable capacitance for $C_{cbl}/R_{cbl}=5\ 000$, 400 Ω series resistance	514
Figure T.24 – Cable capacitance for $C_{cbl}/R_{cbl}=10\ 000$, 100 Ω series resistance	515
Figure T.25 – Cable capacitance for $C_{cbl}/R_{cbl}=10\ 000$, 200 Ω series resistance	515
Figure T.26 – Cable capacitance for $C_{cbl}/R_{cbl}=10\ 000$, 300 Ω series resistance	516
Figure T.27 – Cable capacitance for $C_{cbl}/R_{cbl}=10\ 000$, 400 Ω series resistance	516
Figure T.28 – Network power supply connections	519
Figure T.29 – Grounding and shielding	520
Figure U.1 – Type 24-3 network with linear connection	521
Figure U.2 – Type 24-3 network with T-branch connection	521
Figure U.3 – Type 24-3 network with a combination of linear connections and T-branch connections	522
Figure U.4 – Type 24-3 network with point-to-point connection	522
Figure U.5 – Type 24-3 6-conductor cable structure	522
Figure U.6 – Type 24-3 8-conductor cable structure	523
Figure U.7 – Type 24-3 Interconnecting wiring	524
Figure U.8 – Tap for two branches	525

Figure U.9 – Power supply from C1 master	525
Figure U.10 – Power supply from power adaptor	526
Figure U.11 – Connection of external power to devices	526
Figure U.12 – Power adaptor block diagram	527
Figure U.13 – MAU circuit for the power adaptor	528
Figure U.14 – MAU circuit for the external power device for upstream port	529
Figure U.15 – MAU circuit for the external power device for downstream port	530
Figure U.16 – Voltage drop calculation model for a linear connection	531
Figure U.17 – Power voltage drop model for a T-branch connection	532
Figure V.1 – Resource allocation example A	533
Figure V.2 – Resource allocation example B	534
Figure V.3 – Resource allocation example C	535
Table 1 – Data encoding rules	90
Table 2 – Ph-STATUS indication truth table	91
Table 3 – Jabber indications	91
Table 4 – Primitives and parameters in DLL-PhL interface	105
Table 5 – PH-START primitives and parameters	108
Table 6 – PH-DATA primitives and parameters	108
Table 7 – Ph-Param service primitives and parameters	109
Table 8 – Ph-Param service primitive parameter	109
Table 9 – Ph-Data service primitives and parameters	110
Table 10 – Ph-Data service primitive parameter	110
Table 11 – Ph-Clock-Sync service primitives and parameters	111
Table 12 – Ph-Clock-Sync service primitive parameter	111
Table 13 – Parameter names and values for Ph-SET-VALUE request	113
Table 14 – Parameter names for Ph-EVENT indication	113
Table 15 – Summary of Ph-management services and primitives	115
Table 16 – Reset primitives and parameters	116
Table 17 – Values of PhM-Status for the Reset service	116
Table 18 – Set value primitives and parameters	117
Table 19 – Mandatory PhE-variables	117
Table 20 – Permissible values of PhE-variables	117
Table 21 – Values of PhM-Status for the set-value service	118
Table 22 – Get value primitives and parameters	118
Table 23 – Current values of PhE-variables	118
Table 24 – Values of PhM-Status for the get value service	119
Table 25 – Event primitive and parameters	119
Table 26 – New values of PhE-variables	119
Table 27 – Parameter names and values for management	120
Table 28 – PH-RESET	122
Table 29 – Ph-SET-VALUE	122
Table 30 – PhL variables	123

Table 31 – Ph-GET-VALUE	124
Table 32 – Ph-EVENT	125
Table 33 – PhL events	125
Table 34 – Parameter names and values for Ph-SET-VALUE request.....	126
Table 35 – Physical device configuration information table	127
Table 36 – System configuration related information table	128
Table 37 – PhL synchronization management information table	129
Table 38 – Physical communication resource management information table	130
Table 39 – Ph-RESET primitives and parameters.....	132
Table 40 – Ph-RESET service primitive parameter description.....	132
Table 41 – Ph-SET-VALUE primitives and parameters	133
Table 42 – Ph-SET-VALUE primitive parameter status	133
Table 43 – Ph-GET-VALUE service primitives and parameters.....	134
Table 44 – Ph-EVENT service primitive and parameters	134
Table 45 – Ph-SYNC service primitives and parameters	135
Table 46 – Signals at DTE-DCE interface	140
Table 47 – Signal levels for an exposed DTE-DCE interface	141
Table 48 – MDS bus reset.....	151
Table 49 – Signals at the MIS-MDS interface.....	151
Table 50 – TMs and corresponding parameters	165
Table 51 – Working mode under carrier mode A	166
Table 52 – Working mode under carrier mode B	166
Table 53 – Manchester encoding rules.....	169
Table 54 – MDS timing characteristics	172
Table 55 – MDS data encoding rules	172
Table 56 – SL bit and TxSL signal assignment.....	179
Table 57 – SL bit and RxSL signal assignment	180
Table 58 – SL bit and TxSL signal assignment.....	181
Table 59 – SL bit and RxSL signal assignment	181
Table 60 – SL bit and TxSL signal assignment.....	181
Table 61 – SL bit and RxSL signal assignment	182
Table 62 – Coding and decoding rules	182
Table 63 – Decoding rules for the idle states	183
Table 64 – Coding rules for the reset PhPDU.....	184
Table 65 – Decoding rules of the reset PhPDU	184
Table 66 – Type 24-1 MDS timing characteristics	187
Table 67 – Type 24-3 Manchester coding MDS timing characteristics	187
Table 68 – Type 24-3 NRZI coding MDS timing characteristics	188
Table 69 – MDS data encoding rules of Manchester coding	188
Table 70 – MDS data encoding rules of NRZI coding	189
Table 71 – RS code mode.....	192
Table 72 – Convolutional code mode	192
Table 73 – Bit interleaving parameters.....	194

Table 74 – OFDM configuration parameters	195
Table 75 – Modulation Coding Scheme in carrier mode A	196
Table 76 – Modulation Coding Scheme in carrier mode B	196
Table 77 – Minimum services at MDS-MAU interface	197
Table 78 – Signal levels for an exposed MDS-MAU interface	198
Table 79 – MDS-MAU interface definitions: 5 Mbit/s, voltage-mode, coaxial wire	199
Table 80 – MDS-MAU interface 5 Mbit/s, optical fiber medium	200
Table 81 – Services of the MDS-MAU interface.....	201
Table 82 – Minimum services at MAU interface.....	203
Table 83 – Signal levels for an exposed MAU interface.....	204
Table 84 – Minimum services of the MDS-MAU interface	204
Table 85 – Signal levels for an exposed MDS-MAU interface ($V_{DD}=5\text{ V}$)	205
Table 86 – Minimum services at MDS-MAU interface	206
Table 87 – Allowable constellation diagram errors in different modulation modes.....	208
Table 88 – System transmission parameters.....	208
Table 89 – Bit-rate-dependent quantities of voltage-mode networks.....	209
Table 90 – MAU transmit level specification summary.....	212
Table 91 – MAU transmit timing specification summary for 31,25 kbit/s operation	212
Table 92 – MAU transmit timing specification summary for $\geq 1\text{ Mbit/s}$ operation.....	212
Table 93 – MAU receive circuit specification summary	216
Table 94 – Network powered device characteristics	219
Table 95 – Network power supply requirements	219
Table 96 – Test cable attenuation limits	221
Table 97 – Recommended color coding of cables in North America	223
Table 98 – MAU transmit level specification summary.....	227
Table 99 – MAU transmit timing specification summary.....	227
Table 100 – MAU receive circuit specification summary	230
Table 101 – Network powered device characteristics	232
Table 102 – Network power supply requirements	232
Table 103 – Type 3 cable color specification.....	241
Table 104 – MAU transmit level specification summary.....	244
Table 105 – MAU transmit timing specification summary.....	244
Table 106 – Receive circuit specification summary	246
Table 107 – Network power supply requirements	249
Table 108 – Transmit level specification summary for current-mode MAU	255
Table 109 – Transmit timing specification summary for current-mode MAU	255
Table 110 – Receive circuit specification summary for current-mode MAU	257
Table 111 – Network power supply requirements	258
Table 112 – Bit-rate-dependent quantities of high-speed ($\geq 1\text{ Mbit/s}$) dual-fiber networks	261
Table 113 – Transmit level and spectral specification summary	263
Table 114 – Transmit timing specification summary	263
Table 115 – Receive circuit specification summary	264

Table 116 – Transmit and receive level and spectral specifications for an optical active star	267
Table 117 – Timing characteristics of an optical active star	268
Table 118 – Transmit level and spectral specification summary	269
Table 119 – Transmit and receive level and spectral specifications for an optical active star	271
Table 120 – Transmit control line definitions 5 Mbit/s, voltage-mode, coaxial wire	273
Table 121 – Receiver data output definitions: 5 Mbit/s, voltage-mode, coaxial wire	274
Table 122 – Receiver carrier output definitions: 5 Mbit/s, voltage-mode, coaxial wire	274
Table 123 – Coaxial wire medium interface – transmit specifications	275
Table 124 – Coaxial wire medium interface – receive	276
Table 125 – Coaxial wire medium interface – general	277
Table 126 – 5 Mbit/s, voltage-mode, coaxial wire transformer electrical specifications	278
Table 127 – Coaxial spur cable specifications	282
Table 128 – Coaxial trunk cable specifications	282
Table 129 – Transmit control line definitions 5 Mbit/s, optical fiber medium	284
Table 130 – Fiber medium interface 5,0 Mbit/s, optical	284
Table 131 – Fiber signal specification 5 Mbit/s, optical medium, short range	285
Table 132 – Fiber signal specification 5 Mbit/s, optical medium, medium range	286
Table 133 – Fiber signal specification 5 Mbit/s, optical medium, long range	287
Table 134 – NAP requirements	289
Table 135 – Mixing devices from different categories	292
Table 136 – Input Impedances of bus interfaces and power supplies	295
Table 137 – Required CMRR	298
Table 138 – Network powered device characteristics for the 31,25 kbit/s voltage-mode MAU	298
Table 139 – Network power supply requirements for the 31,25 kbit/s voltage-mode MAU	299
Table 140 – Electrical characteristics of fieldbus interfaces	304
Table 141 – Electrical characteristics of power supplies	306
Table 142 – Characteristics for non intrinsic safety	310
Table 143 – Characteristics using repeaters	310
Table 144 – Cable specifications	312
Table 145 – Maximum cable length for the different transmission speeds	312
Table 146 – Characteristics for intrinsic safety	315
Table 147 – Cable specification (function- and safety-related)	318
Table 148 – Maximum cable length for the different transmission speeds	318
Table 149 – Electrical characteristics of the intrinsically safe interface	321
Table 150 – Maximum safety values	325
Table 151 – Characteristic features	326
Table 152 – Characteristics of optical transmitters for multi-mode glass fiber	329
Table 153 – Characteristics of optical transmitters for single-mode glass fiber	330
Table 154 – Characteristics of optical transmitters for plastic fiber	330
Table 155 – Characteristics of optical transmitters for 200/230 µm glass fiber	330

Table 156 – Characteristics of optical receivers for multi-mode glass fiber	331
Table 157 – Characteristics of optical receivers for single-mode glass fiber	331
Table 158 – Characteristics of optical receivers for plastic fiber	331
Table 159 – Characteristics of optical receivers for 200/230 µm glass fiber.....	332
Table 160 – Permissible signal distortion at the electrical input of the optical transmitter	332
Table 161 – Permissible signal distortion due to the optical transmitter.....	333
Table 162 – Permissible signal distortion due to the optical receiver.....	334
Table 163 – Permissible signal influence due to internal electronic circuits of a coupling component.....	334
Table 164 – Maximum chaining of standard optical links without retiming	335
Table 165 – Services of the MDS-MAU interface, RS-485, Type 4	336
Table 166 – Bit rate dependent quantities twisted pair wire medium MAU	338
Table 167 – Incoming interface signals	340
Table 168 – Outgoing interface signals	340
Table 169 – Remote bus cable characteristics	341
Table 170 – Bit rate dependent quantities optical MAU	343
Table 171 – Remote bus fiber optic cable length.....	344
Table 172 – Encoding rules	344
Table 173 – Transmit level and spectral specification summary for an optical MAU.....	344
Table 174 – Optical MAU receive circuit specification summary	346
Table 175 – Specification of the fiber optic waveguide	346
Table 176 – Specification of the single fiber.....	347
Table 177 – Specification of the cable sheath and mechanical properties of the cable	347
Table 178 – Recommended further material properties of the cable	347
Table 179 – Specification of the fiber optic waveguide	348
Table 180 – Specification of the single fiber.....	348
Table 181 – Specification of the cable sheath and mechanical properties of the cable	349
Table 182 – Specification of the standard test fiber for an optical MAU	349
Table 183 – Power requirements for PSE, PI and PD.....	353
Table 184 – Additional requirements for PSE	353
Table 185 – Additional requirements for PD	354
Table 186 – Power requirements for PSE, PI and PD.....	355
Table 187 – Power requirements for PD dynamic change of current.....	356
Table 188 – Transmission rate support	361
Table 189 – Transmission data parameters.....	361
Table 190 – Possible slave input signals.....	363
Table 191 – Possible slave output signals.....	363
Table 192 – Valid slave output signals	364
Table 193 – Specifications of the clock adjustment times	364
Table 194 – Optical signal delay in a slave	364
Table 195 – Basic functions of the connection	365
Table 196 – Pass-through topology limits.....	372
Table 197 – T-branch topology limits	373

Table 198 – Terminating resistor requirements	373
Table 199 – Pass-through topology limits	377
Table 200 – T-branch topology limits	377
Table 201 – Terminating resistor requirements – flat cable	378
Table 202 – Terminating resistor requirements – round cable	378
Table 203 – 24 V power supply specifications	380
Table 204 – 24 V power consumption specifications	380
Table 205 – MAU summary	383
Table 206 – Type 24-1 Cable specification	386
Table 207 – Transmitter specification	387
Table 208 – Receiver specification	387
Table 209 – Pulse width for Type 24-3	388
Table 210 – Type 24-1 Specification of transformer	389
Table 211 – Device parameters	396
Table 212 – Transmit amplitude limits	399
Table 213 – Digital receiver specifications	402
Table 214 – High impedance device characteristics	404
Table 215 – Low impedance device characteristics	404
Table 216 – Secondary device characteristics	405
Table 217 – Network power supply characteristics	406
Table 218 – Barrier characteristics	407
Table 219 – Miscellaneous hardware required characteristics	409
Table 220 – Miscellaneous hardware recommended characteristics	410
Table 221 – Transmission medium interface	411
Table A.1 – Internal connector dimensions	414
Table A.2 – Contact assignments for the external connector for harsh industrial environments	415
Table A.3 – Contact assignments for the external connector for typical industrial environments	419
Table A.4 – Fixed (device) side connector dimensions	419
Table A.5 – Free (cable) side connector dimensions	420
Table A.6 – Connector dimensions	421
Table B.1 – Typical cable specifications	422
Table B.2 – Recommended maximum spur lengths versus number of communication elements	423
Table C.1 – Optical passive star specification summary: example	424
Table D.1 – Passive star topology	426
Table D.2 – Active star topology	427
Table E.1 – Alternate fibers for dual-fiber mode	429
Table E.2 – Alternate fibers for single-fiber mode	429
Table F.1 – Connector requirements	430
Table F.2 – NAP connector pin definition	432
Table H.1 – 5 Mbit/s, voltage-mode, coaxial wire receiver output definitions	445
Table H.2 – Coaxial wire medium toroid specification	447

Table I.1 – Contact assignments for the external connector for harsh industrial environments	450
Table I.2 – Contact designations 9-pin sub-D connector	452
Table I.3 – Contact designations	453
Table I.4 – Contact designations 4-pin M-12	453
Table K.1 – Example link budget calculation for 62,5/125 μm multi-mode glass fiber	464
Table K.2 – Example link budget calculation for 9/125 μm single mode glass fiber	465
Table K.3 – Example link budget calculation for 980/1 000 μm multi-mode plastic fiber	465
Table K.4 – Example level budget calculation for 200/230 μm multi-mode glass fiber	466
Table M.1 – Pin assignment of the 9-position subminiature D connector	469
Table M.2 – Pin assignment of the terminal connector	470
Table M.3 – Type 8 fiber optic hybrid connector dimensions	473
Table O.1 – Transmitter specifications	477
Table O.2 – Receiver specifications	478
Table O.3 – Cable specifications (example)	478
Table O.4 – System data of the optical transmission line at 650 nm	479
Table R.1 – PhL-B cable specifications	489
Table R.2 – PhL-P flat cable specifications	490
Table R.3 – PhL-P round cable specifications – preferred	491
Table R.4 – PhL-P round cable specifications – alternate	492
Table T.1 – Device and cable parameters	505
Table U.1 – Type 24-3 6-conductor cable specification	523
Table U.2 – Type 24-3 8-conductor cable specification	524
Table U.3 – Specification of supply power	527
Table U.4 – Classification of power load	527
Table U.5 – Specification of power load	528
Table W.1 – RS code (255, 247) generating polynomial	536
Table W.2 – RS code (255, 239) generating polynomial	536
Table W.3 – RS code (255, 223) generating polynomial	537

INTERNATIONAL ELECTROTECHNICAL COMMISSION

INDUSTRIAL COMMUNICATION NETWORKS – FIELD BUS SPECIFICATIONS –

Part 2: Physical layer specification and service definition

FOREWORD

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Attention is drawn to the fact that the use of some of the associated protocol types is restricted by their intellectual-property-right holders. In all cases, the commitment to limited release of intellectual-property-rights made by the holders of those rights permits a layer protocol type to be used with other layer protocols of the same type, or in other type combinations explicitly authorized by their respective intellectual property right holders.

NOTE 1 Combinations of protocol types are specified in the IEC 61784-1 series and the IEC 61784-2 series.

IEC 61158-2 has been prepared by subcommittee 65C: Industrial networks, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This seventh edition cancels and replaces the sixth edition published in 2014. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) Type 12 added power option to 100BASE-TX in Clause 29;
- b) enhanced Type 24 specification in Clause 33, Annex S and Annex U;
- c) new Type 28 specification;
- d) LVDS wire medium up to 100 Mbit/s of Type 12 is removed.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65C/1200/FDIS	65C/1241/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

NOTE 2 Slight variances from the directives have been allowed by the IEC Central Office to provide continuity of subclause numbering with prior editions.

A list of all the parts of the IEC 61158 series, under the general title *Industrial communication networks – Fieldbus specifications*, can be found on the IEC web site.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The "colour inside" logo on the cover page of this document indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

0 INTRODUCTION

0.1 General

This part of IEC 61158 is one of a series produced to facilitate the interconnection of automation system components. It is related to other standards in the set as defined by the "three-layer" fieldbus reference model described in IEC 61158-1.

0.2 Physical layer overview

The primary aim of this document is to provide a set of rules for communication expressed in terms of the procedures to be carried out by peer Ph-entities at the time of communication.

The physical layer receives data units from the data-link Layer, encodes them, if necessary by adding communications framing information, and transmits the resulting physical signals to the transmission medium at one node. Signals are then received at one or more other node(s), decoded, if necessary by removing the communications framing information, before the data units are passed to the data-link Layer of the receiving device.

0.3 Document overview

This document comprises physical layer specifications corresponding to many of the different DL-Layer protocol Types specified in IEC 61158 series.

NOTE 1 The protocol Type numbers used are consistent throughout the IEC 61158 series.

NOTE 2 Specifications for Types 1, 2, 3, 4, 8, 12, 16, 18, 20, 24 and 28 are included. Type 7 uses Type 1 specifications. The other Types do not use any of the specifications given in this document.

NOTE 3 For ease of reference, Type numbers are given in clause names. This means that the specification given therein applies to this Type, but does not exclude its use for other Types.

NOTE 4 It is up to the user of this document to select interoperating sets of provisions. Refer to the IEC 61784-1 series or the IEC 61784-2 series for standardized communication profiles based on the IEC 61158 series.

A general model of the physical layer is shown in Figure 1.

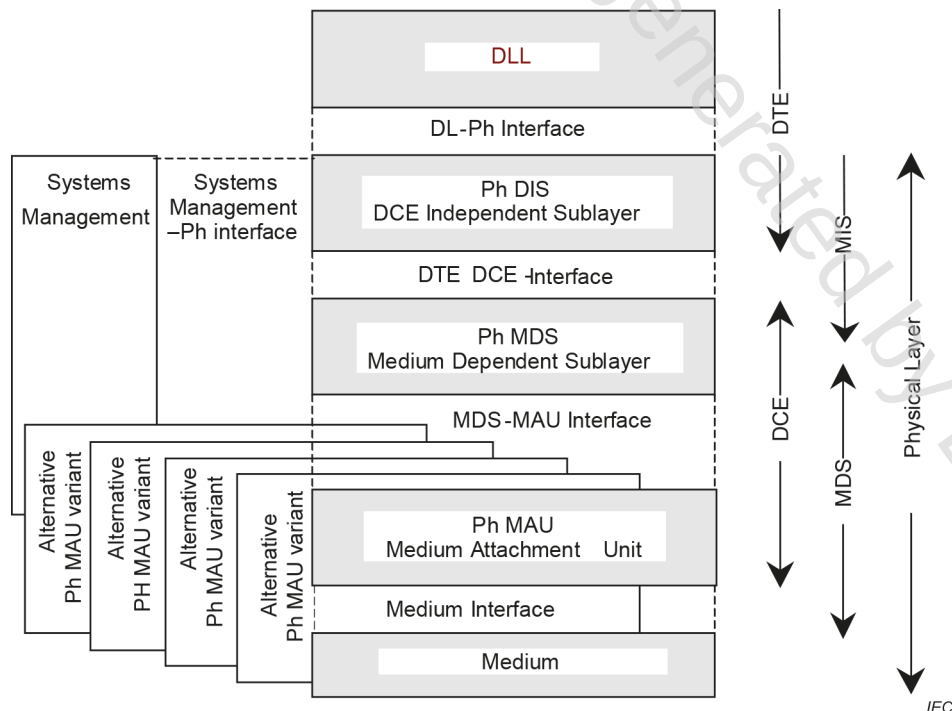


Figure 1 – General model of physical layer

NOTE 5 The protocol types use a subset of the structure elements.

NOTE 6 Since Type 8 uses a more complex DIS than the other types, it uses the term MIS to differentiate.

The common characteristics for all variants and types are as follows:

- digital data transmission;
- no separate clock transmission;
- either half-duplex communication (bi-directional but in only one direction at a time) or full-duplex communication.

0.4 Major physical layer variations specified in this document

0.4.1 Type 1 media

0.4.1.1 Type 1: Wire media

For twisted-pair wire media, Type 1 specifies two modes of coupling and different signaling speeds as follows:

- a) voltage mode (parallel coupling), 150 Ω , data rates from 31,25 kbit/s to 25 Mbit/s;
- b) voltage mode (parallel coupling), 100 Ω , 31,25 kbit/s;
- c) current mode (serial coupling), 1,0 Mbit/s including two current options.

The voltage mode variations may be implemented with inductive coupling using transformers. This is not mandatory if the isolation requirements of this document are met by other means.

The Type 1 twisted-pair (or untwisted-pair) wire medium physical layer provides the options:

- no power via the bus conductors; not intrinsically safe;
- power via the bus conductors; not intrinsically safe;
- no power via the bus conductors; intrinsically safe;
- power via the bus conductors; intrinsically safe.

0.4.1.2 Type 1: Optical media

The major variations of the Type 1 optic fiber media are as follows:

- dual fiber mode, data rates from 31,25 kbit/s to 25 Mbit/s;
- single fiber mode, 31,25 kbit/s.

0.4.2 Type 2: Coaxial wire and optical media

Type 2 specifies the following variants:

- coaxial copper wire medium, 5 Mbit/s;
- optical fiber medium, 5 Mbit/s;
- network access port (NAP), a point-to-point temporary attachment mechanism that can be used for programming, configuration, diagnostics or other purposes;
- repeater machine sublayers (RM, RRM) and redundant physical layers.

0.4.3 Type 3: Twisted-pair wire and optical media

Type 3 specifies the following synchronous transmission:

- a) twisted-pair wire medium, 31,25 kbit/s, voltage mode (parallel coupling) with the options:
 - power via the bus conductors: not intrinsically safe;
 - power via the bus conductors: intrinsically safe;

and the following asynchronous transmission variants:

- b) twisted-pair wire medium, up to 12 Mbit/s, TIA-485-A;
- c) optical fiber medium, up to 12 Mbit/s, with fiber type A4a of IEC 60793-2-40 and fiber type A3c of IEC 60793-2-30.

0.4.4 Type 4: Wire medium

Type 4 specifies wire media with the following characteristics:

- RS-485 wire medium up to 76,8 kbit/s;

0.4.5 Type 8: Twisted-pair wire and optical media

The physical layer also allows transmitting data units that have been received through a medium access by the transmission medium directly through another medium access and its transmission protocol to another device.

Type 8 specifies the following variants:

- twisted-pair wire medium, up to 16 Mbit/s;
- optical fiber medium, up to 16 Mbit/s.

The general characteristics of these transmission media are as follows:

- full-duplex transmission;
- non-return-to-zero (NRZ) coding.

The wire media type provides the following options:

- no power supply via the bus cable, not intrinsically safe;
- power supply via the bus cable and on additional conductors, not intrinsically safe.

0.4.6 Type 12: Wire medium

Type 12 specifies wire media with the following characteristics:

- two pair of wires carrying two separate power supply channels combined with signal transmission.

0.4.7 Type 16: optical media

Type 16 specifies a synchronous transmission using optical fiber medium, at 2 Mbit/s, 4 Mbit/s, 8 Mbit/s and 16 Mbit/s.

0.4.8 Type 18: Media

0.4.8.1 Type 18: Basic media

The Type 18-PhL-B specifies a balanced transmission signal over a shielded 3-core twisted cable. Communication data rates as high as 10 Mbit/s and transmission distances as great as 1,2 km are specified.

0.4.8.2 Type 18: Powered media

The Type 18-PhL-P specifies a balanced transmission signal over a 4-core unshielded cable in both flat and round configurations with conductors specified for communications signal and network-embedded power distribution. Communication data rates as high as 2,5 Mbit/s and transmission distances as great as 500 m are specified.

0.4.9 Type 20: Media

Type 20 uses binary phase continuous Frequency Shift Keying (FSK). A relatively high frequency current is superimposed on a low-frequency analog current, which is usually in 4 mA to 20 mA range. The digital signal and analog signal share the same medium, but differ in frequency contents. The communicating devices signal with either current or voltage, and all signaling appear as voltage when sensed across low impedance. Thus, digital signaling is an extension of conventional analog signaling.

The physical layer commonly uses twisted pair copper cable as its medium and provides solely digital or simultaneous digital and analog communication to distances of at least 1 500 m (ca. 5 000 feet). Maximum communication distances vary depending on network construction and environmental conditions.

0.4.10 Type 24: Media

0.4.10.1 Type 24: Basic media

Type 24 specifies twisted-pair wire medium. The general characteristics of this transmission medium are as follows:

- TIA-485-A bus interface with galvanic isolation using transformer;
- up to 10 Mbit/s;
- half-duplex transmission;
- Manchester coding.

0.4.10.2 Type 24: Powered media

The powered media type provides the following options:

- TIA-485-A bus interface without galvanic isolation using transformer;
- up to 32 Mbit/s;
- half-duplex transmission;
- Manchester coding or NRZI coding;
- power via the bus conductors.

0.4.11 Type 28: Media

Type 28 uses Orthogonal Frequency Division Multiplexing (OFDM) technology. The frequency subcarrier ranges from 1,536 MHz to 32,256 MHz. The transmission distances are up to 500 m on a single bus. The analog signal shall be delivered on the medium that connected to each device in network.

Type 28 specifies the following synchronous transmission:

- a) twisted-pair wire medium, up to 100 Mbit/s;
- b) coaxial wire medium, up to 100 Mbit/s.

The general characteristics of these transmission media are as follows:

- a) full-duplex transmission;
- b) OFDM coding.

0.5

Patent declaration

The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of a patent. IEC takes no position concerning the evidence, validity, and scope of this patent right.

The holder of this patent right has assured IEC that s/he is willing to negotiate licences under reasonable and non-discriminatory terms and conditions with applicants throughout the world. In this respect, the statement of the holder of this patent right is registered with IEC. Information may be obtained from the patent database available at <http://patents.iec.ch>.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights other than those in the patent database. IEC shall not be held responsible for identifying any or all such patent rights.

INDUSTRIAL COMMUNICATION NETWORKS – FIELDBUS SPECIFICATIONS –

Part 2: Physical layer specification and service definition

1 Scope

This part of IEC 61158 specifies the requirements for fieldbus component parts. It also specifies the media and network configuration requirements necessary to ensure agreed levels of

- a) data integrity before data-link layer error checking;
- b) interoperability between devices at the physical layer.

The fieldbus physical layer conforms to layer 1 of the OSI 7-layer model as defined by ISO/IEC 7498 with the exception that, for some types, frame delimiters are in the physical layer while for other types they are in the data-link layer.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE All parts of the IEC 61158 series, as well as the IEC 61784-1 series and the IEC 61784-2 series are maintained simultaneously. Cross-references to these documents within the text therefore refer to the editions as dated in this list of normative references.

IEC 60050 (all parts), *International Electrotechnical Vocabulary* (available at <http://www.electropedia.org>)

IEC 60079-11, *Explosive atmospheres – Part 11: Equipment protection by intrinsic safety "i"*

IEC 60079-14:2007¹, *Explosive atmospheres – Part 14: Electrical installations design, selection and erection*

IEC 60079-25, *Explosive atmospheres – Part 25: Intrinsically safe electrical systems*

IEC 60169-17, *Radio-frequency connectors – Part 17: R.F. coaxial connectors with inner diameter of outer conductor 6,5 mm (0,256 in) with screw coupling – Characteristic impedance 50 ohms (Type TNC)*

IEC 60189-1:2018, *Low-frequency cables and wires with PVC insulation and PVC sheath – Part 1: General test and measuring methods*

IEC 60255-22-1:1988², *Electrical relays – Part 22-1: Electrical disturbance tests for measuring relays and protection equipment – Section 1: 1 MHz burst disturbance tests*

¹ A 2013 edition exists but the listed edition applies.

² This publication was withdrawn.

IEC 60364-4-41, *Low-voltage electrical installations – Part 4-41: Protection for safety – Protection against electric shock*

IEC 60364-5-54, *Low voltage electrical installations – Part 5-54: Selection and erection of electrical equipment – Earthing arrangements and protective conductors*

IEC 60529, *Degrees of protection provided by enclosures (IP Code)*

IEC 60603-7-4, *Connectors for electronic equipment – Part 7-4: Detail specification for 8-way, unshielded, free and fixed connectors, for data transmissions with frequencies up to 250 MHz*

IEC 60754-2, *Test on gases evolved during combustion of materials from cables – Part 2: Determination of acidity (by pH measurement) and conductivity*

IEC 60793 (all parts), *Optical fibres*

IEC 60793-2:2019, *Optical fibres – Part 2: Product specifications – General*

IEC 60793-2-30:2015, *Optical fibres – Part 2-30: Product specifications – Sectional specification for category A3 multimode fibres*

IEC 60793-2-40:2021, *Optical fibres – Part 2-40: Product specifications – Sectional specification for category A4 multimode fibres*

IEC 60794-1-2:2003³, *Optical fibre cables – Part 1-2: Generic specification – Basic optical cable test procedures*

IEC 60807-3, *Rectangular connectors for frequencies below 3 MHz – Part 3: Detail specification for a range of connectors with trapezoidal shaped metal shells and round contacts – Removable crimp contact types with closed crimp barrels, rear insertion/rear extraction*

IEC 60811-403, *Electric and optical fibre cables – Test methods for non-metallic materials – Part 403: Miscellaneous tests – Ozone resistance test on cross-linked compounds*

IEC 60811-404:2012, *Electric and optical fibre cables – Test methods for non-metallic materials – Part 404: Miscellaneous tests – Mineral oil immersion tests for sheaths*

IEC 61000-4-2, *Electromagnetic compatibility (EMC) – Part 4-2: Testing and measurement techniques – Electrostatic discharge immunity test*

IEC 61000-4-3, *Electromagnetic compatibility (EMC) – Part 4-3: Testing and measurement techniques – Radiated, radio-frequency, electromagnetic field immunity test*

IEC 61000-4-4, *Electromagnetic compatibility (EMC) – Part 4-4: Testing and measurement techniques – Electrical fast transient/burst immunity test*

IEC 61076-2-114:2020, *Connectors for electrical and electronic equipment – Product requirements – Part 2-114: Circular connectors – Detail specification for connectors with M8 screw- locking with power contacts and signal contacts for data transmission up to 100 MHz*

IEC 61131-2:2017, *Industrial-process measurement and control – Programmable controllers – Part 2: Equipment requirements and tests*

³ There exists a new edition of IEC 60794-1-2 (2021). Cross-references to 2003 version is described in informative Annex A.

IEC 61156-1:2007, *Multicore and symmetrical pair/quad cables for digital communications – Part 1: Generic specification*

IEC 61158-3-20:2023, *Industrial communication networks – Fieldbus specifications – Part 3-20: Data-link layer service definition – Type 20 elements*

IEC 61158-4-2:2023, *Industrial communication networks – Fieldbus specifications – Part 4-2: Data-link protocol specification – Type 2 elements*

IEC 61158-4-3:2019, *Industrial communication networks – Fieldbus specifications – Part 4-3: Data-link protocol specification – Type 3 elements*

IEC 61169-8:2007, *Radio-frequency connectors – Part 8: Sectional specification – RF coaxial connectors with inner diameter of outer conductor 6,5 mm (0,256 in) with bayonet lock – Characteristic impedance 50 Ω (type BNC)*

IEC 61210:2010, *Connecting devices – Flat quick-connect terminations for electrical copper conductors – Safety requirements*

IEC 61754-2, *Fibre optic connector interfaces – Part 2: Type BFOC/2,5 connector family*

IEC 61754-13, *Fibre optic connector interfaces – Part 13: Type FC-PC connector*

IEC 61754-22, *Fibre optic connector interfaces – Part 22: Type F-SMA connector family*

IEC 63171, *Connectors for electrical and electronic equipment – Shielded or unshielded free and fixed connectors for balanced single-pair data transmission with current carrying capacity – General requirements and tests*

ISO/IEC 7498 (all parts), *Information technology – Open Systems Interconnection – Basic Reference Model*

ISO/IEC 7498-1:1994, *Information technology – Open Systems Interconnection – Basic Reference Model: The Basic Model*

ISO/IEC 8482, *Information technology – Telecommunications and information exchange between systems – Twisted pair multipoint interconnections*

ISO/IEC/IEEE 8802-3:2021, *Telecommunications and information exchange between systems – Requirements for local and metropolitan area networks – Specific requirements – Part 3: Standard for Ethernet*

ISO 9314-1, *Information processing systems – Fibre Distributed Data Interface (FDDI) Part 1: Token Ring Physical Layer Protocol (PHY)*

ISO/IEC 10731:1994, *Information technology – Open Systems Interconnection – Basic Reference Model – Conventions for the definition of OSI services*

ISO 4892-1, *Plastics – Methods of exposure to laboratory light sources – Part 1: General guidance*

TIA-422-B:1994, *Electrical Characteristics of Balanced Voltage Digital Interface Circuits*

TIA-485-A:1998, *Electrical Characteristics of Generators and Receivers for Use in Balanced Digital Multipoint Systems*